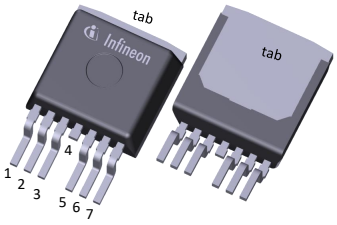
MOSFET

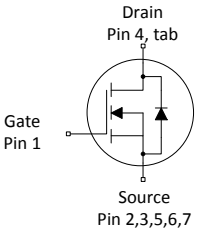
OptiMOS™ 5 Linear FET *2*, 100 V

D²-PAK 7pin



Features

- Ideal for hot-swap and e-fuse applications
- Very low on-resistance $R_{DS(on)}$
- Wide safe operating area SOA
- N-channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21



Product validation

Fully qualified according to JEDEC for Industrial Applications

Table 1 Key performance parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	1.8	mΩ
I_D	259	A
I_{pulse} (V_{DS}=56 V, t_p=10 ms)	10.7	A

Hal Pb RoHS

Part number	Package	Marking	Related links
IPF018N10NM5LF2	PG-TO263-7	18N10LF2	-

Table of contents

1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Continuous drain current [1]	I_D	-	-	259 198 198 31	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=15 V, T_C=100 °C V_{GS}=10 V, T_A=25 °C, R_{thJA}=40 °C/W [2]
Pulsed drain current [3]	$I_{D,pulse}$	-	-	1036	A	T_C=25 °C
Avalanche energy, single pulse [4]	E_{AS}	-	-	1166	mJ	I_D=100 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	375 3.8	W	T_C=25 °C T_A=25 °C, R_{thJA}=40 °C/W [2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

[3] See Diagrams 3 and 4 for more detailed information

[4] See Diagram 14 for more detailed information

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.4	°C/W	-
Thermal resistance, junction - ambient, 6 cm² cooling area [5]	R_{thJA}	-	-	40	°C/W	
Thermal resistance, junction - ambient, minimal footprint	R_{thJA}	-	-	62	°C/W	

[5] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.3	3.1	3.9	V	V_{DS}=V_{GS}, I_D=280 µA
Zero gate voltage drain current	I_{DSS}	-	0.1 10	1 100	µA	V_{DS}=100 V, V_{GS}=0 V, T_j=25 °C V_{DS}=100 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	1.4 1.6	1.7 1.8	mΩ	V_{GS}=15 V, I_D=100 A V_{GS}=10 V, I_D=100 A
Gate resistance	R_G	-	1.3	2.0	Ω	-
Transconductance	g_{fs}	49	97	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=100 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Input capacitance [6]	C_{iss}	-	13000	17000	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Output capacitance [6]	C_{oss}	-	1800	2300	pF	
Reverse transfer capacitance [6]	C_{rss}	-	35	61	pF	
Turn-on delay time	$t_{d(on)}$	-	30	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=100 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r	-	27	-	ns	
Turn-off delay time	$t_{d(off)}$	-	48	-	ns	
Fall time	t_f	-	20	-	ns	

[6] Defined by design. Not subject to production test.

Table 6 Gate charge characteristics [7)]

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	84	-	nC	V_{DD}=50 V, I_D=100 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	41	-	nC	
Gate to drain charge [8)]	Q_{gd}	-	27	41	nC	
Switching charge	Q_{sw}	-	70	-	nC	
Gate charge total [8)]	Q_g	-	165	206	nC	
Gate plateau voltage	$V_{plateau}$	-	6.4	-	V	
Gate charge total, sync. FET	$Q_{g(sync)}$	-	150	-	nC	V_{DS}=0.1 V, V_{GS}=0 to 10 V
Output charge [8)]	Q_{oss}	-	211	281	nC	V_{DS}=50 V, V_{GS}=0 V

7) See "Gate charge waveforms" for parameter definition

8) Defined by design. Not subject to production test.

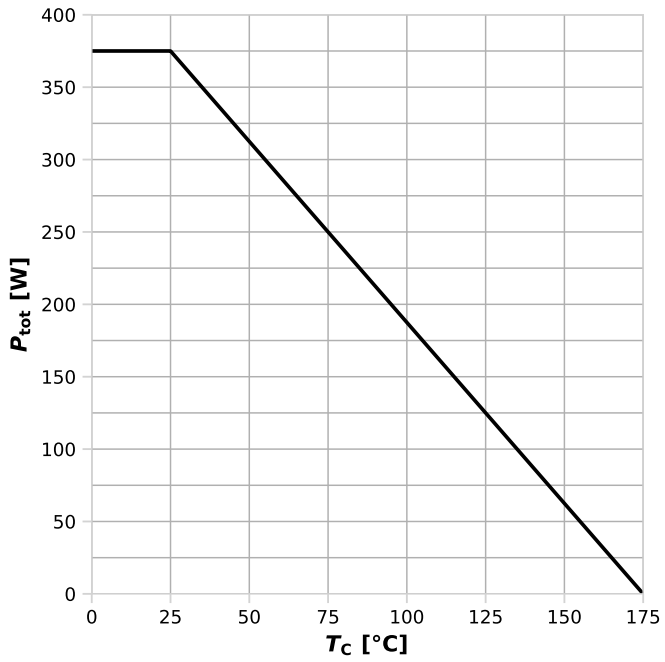
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	227	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	1036	A	
Diode forward voltage	V_{SD}	-	0.86	1.2	V	V_{GS}=0 V, I_F=100 A, T_j=25 °C
Reverse recovery time [9)]	t_{rr}	-	70	140	ns	V_R=50 V, I_F=100 A, di_F/dt=100 A/µs
Reverse recovery charge [9)]	Q_{rr}	-	105	210	nC	

9) Defined by design. Not subject to production test.

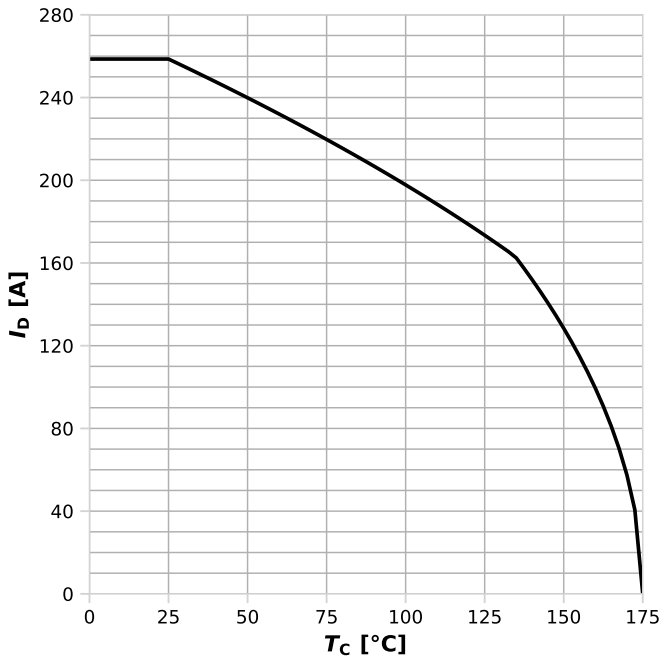
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



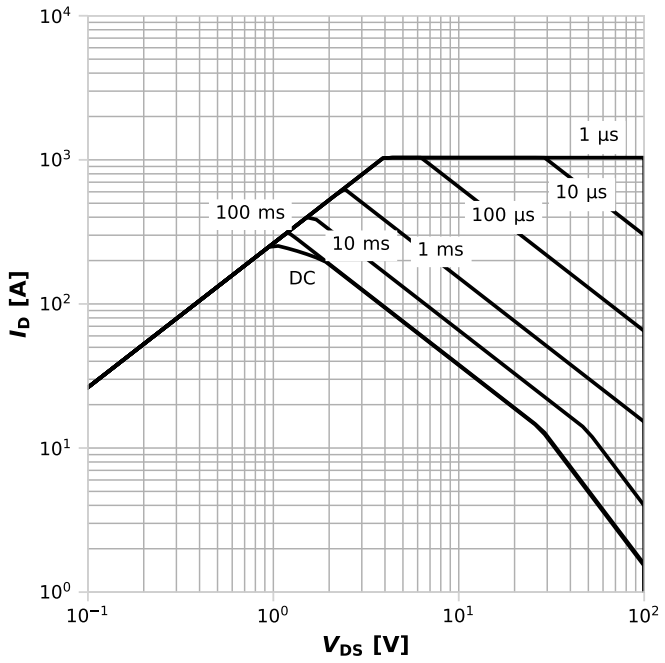
P_{tot}=f(T_C)

Diagram 2: Drain current



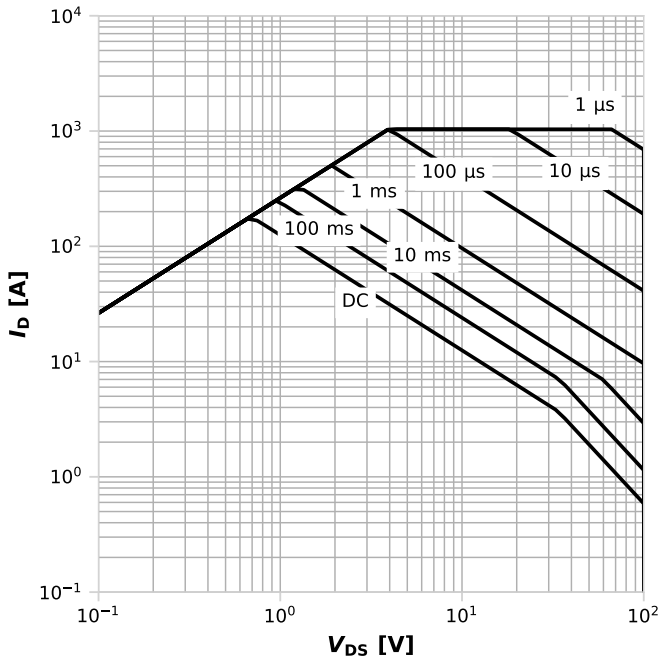
I_D=f(T_C); V_{GS}≥10 V

Diagram 3: Safe operating area



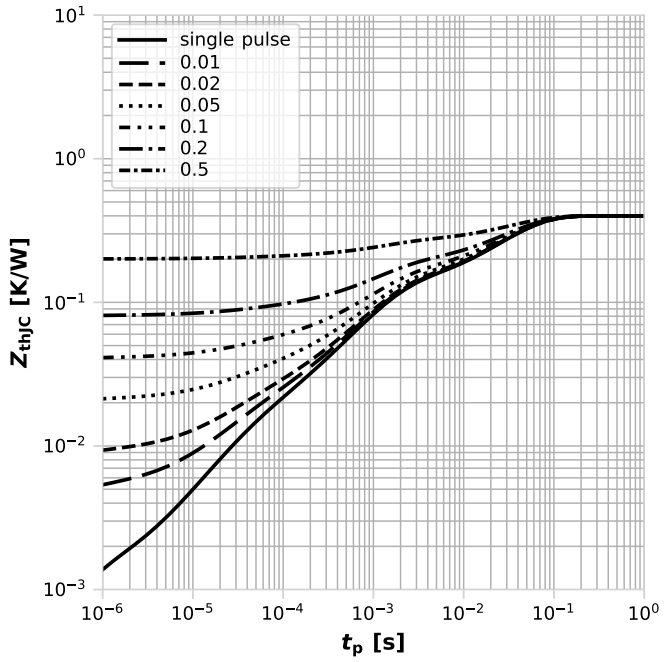
I_D=f(V_{DS}); T_C=25 °C; D=0; parameter: t_p

Diagram 4: Safe operating area



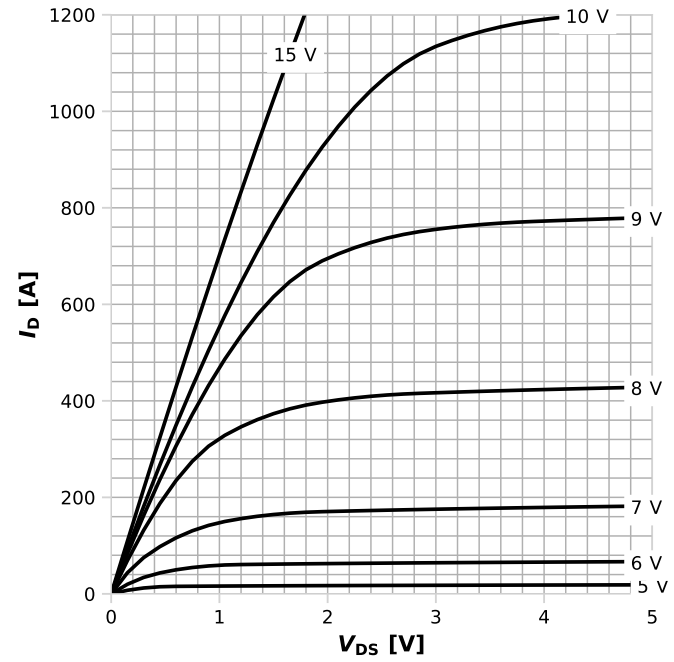
I_D=f(V_{DS}); T_C=125 °C; D=0; parameter: t_p

Diagram 5: Max. transient thermal impedance



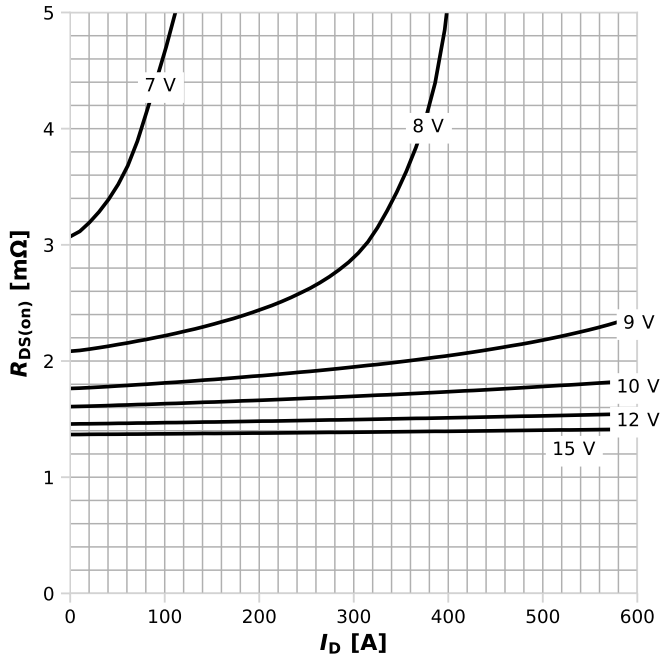
Z_{thJC}=f(t_p); parameter: D=t_p/T

Diagram 6: Typ. output characteristics



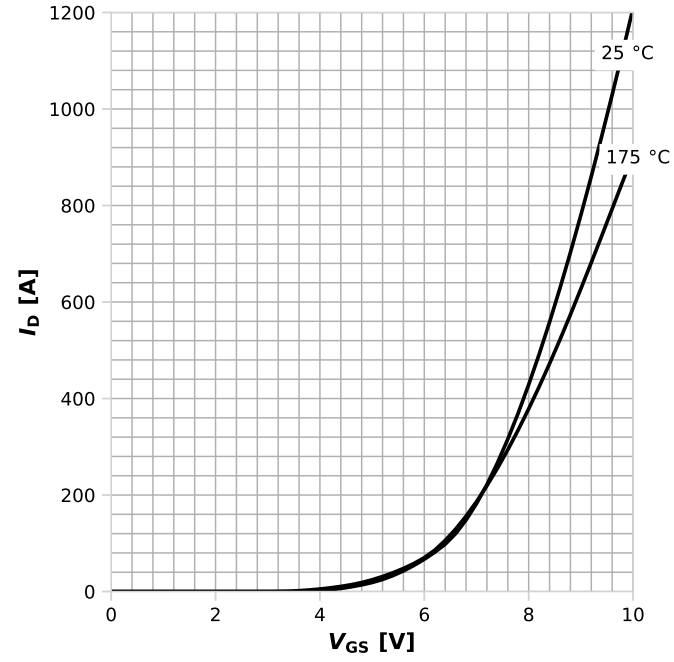
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. drain-source on resistance



$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 8: Typ. transfer characteristics



I_D=f(V_{GS}), |V_{DS}|>2|I_D|$R_{DS(on)max}$; parameter: T_j

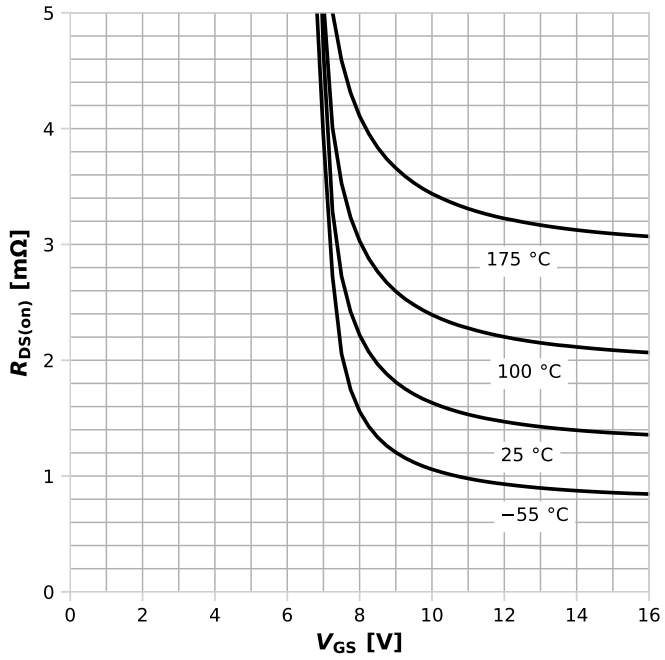
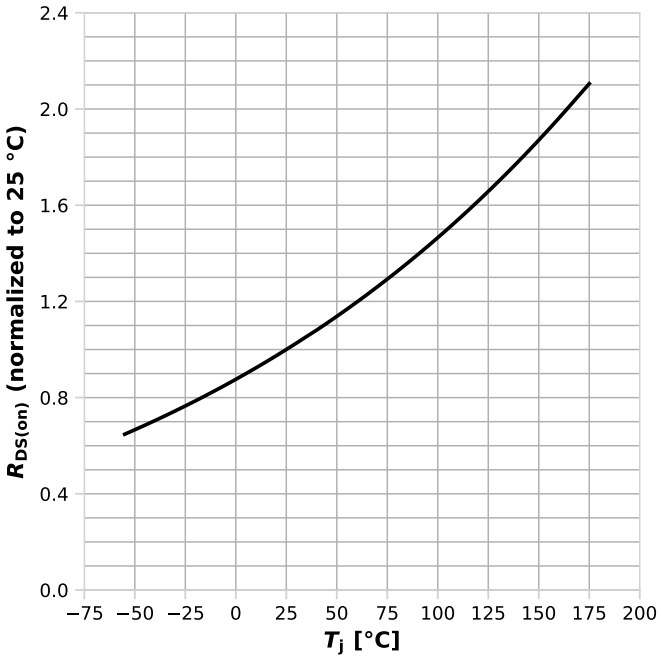
Diagram 9: Typ. drain-source on resistance	Diagram 10: Normalized drain-source on resistance
	
$R_{DS(on)}$=f(V_{GS}), I_D=100 A; parameter: T_j	$R_{DS(on)}$=f(T_j), I_D=100 A, V_{GS}=10 V

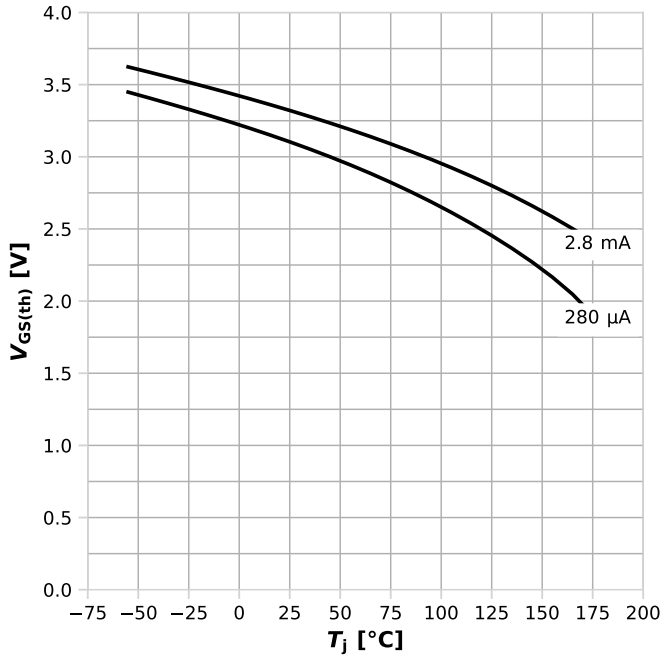
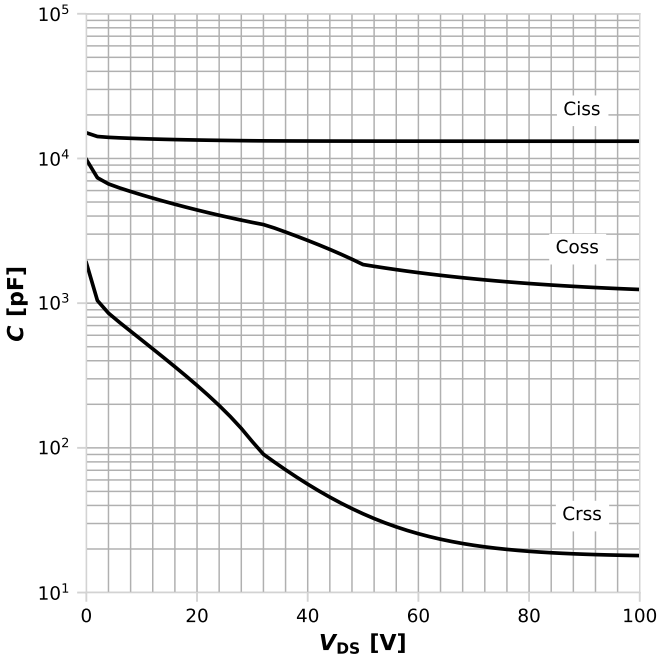
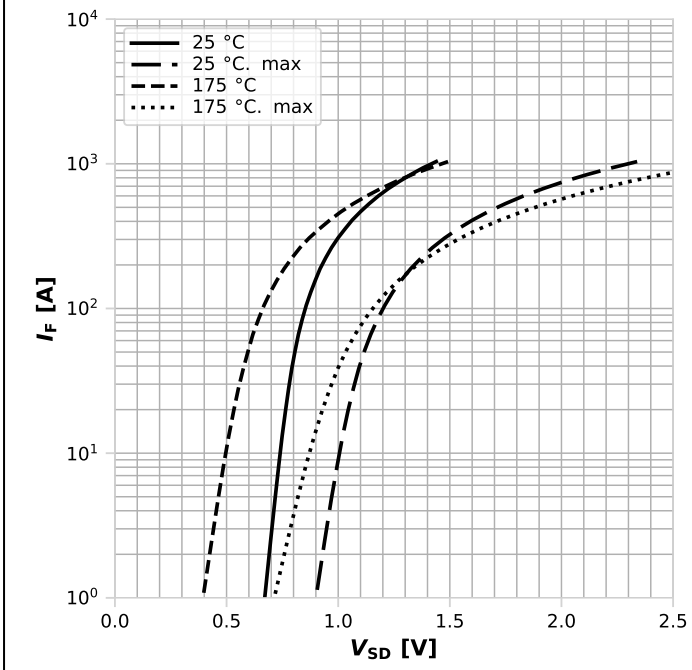
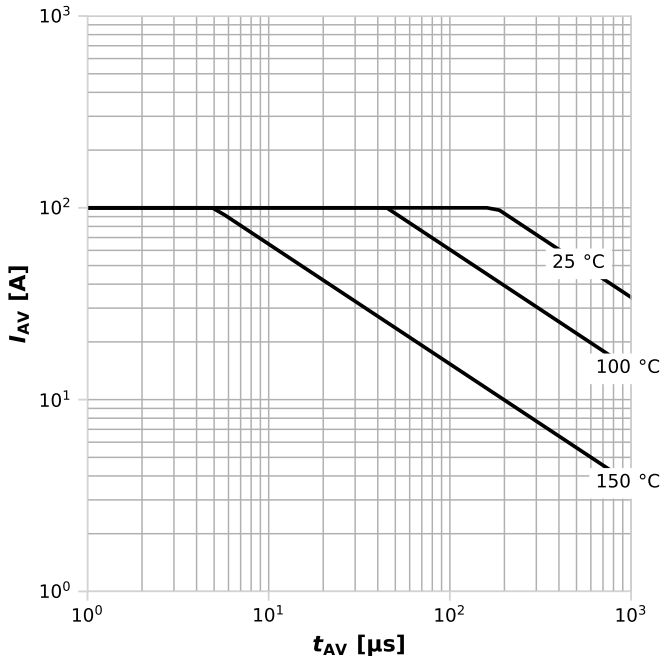
Diagram 11: Typ. gate threshold voltage	Diagram 12: Typ. capacitances
	
$V_{GS(th}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D	C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 13: Forward characteristics of reverse diode



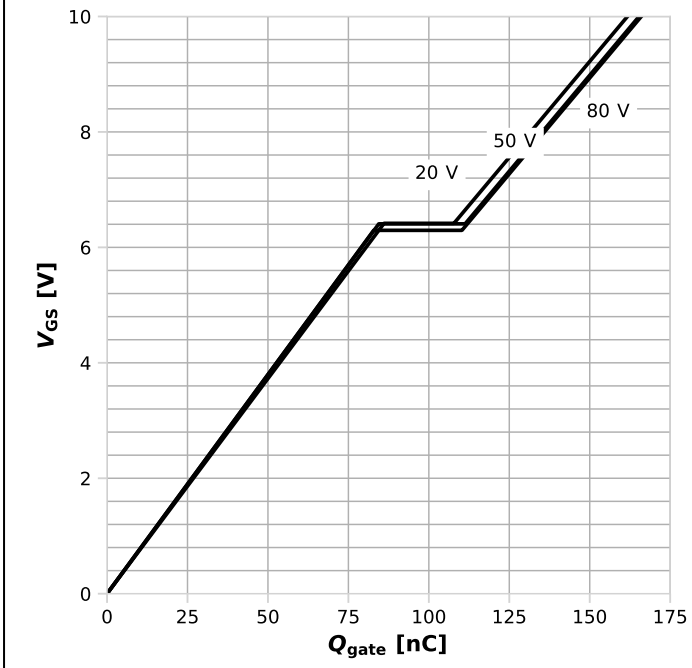
I_F=f(V_{SD}); parameter: T_j

Diagram 14: Avalanche characteristics



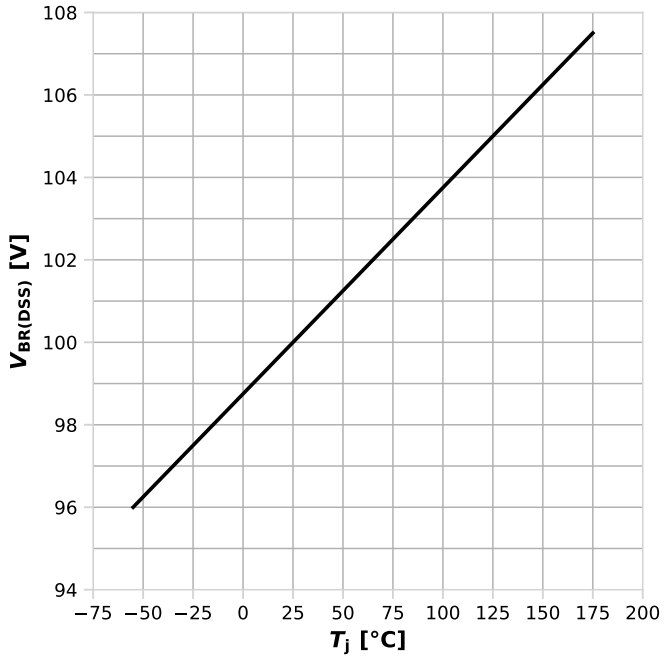
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$

Diagram 15: Typ. gate charge



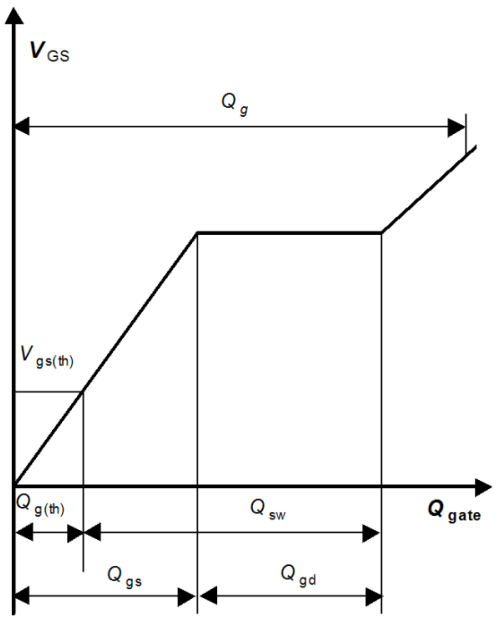
V_{GS}=f(Q_{gate}), I_D=100 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 16: Min. drain-source breakdown voltage



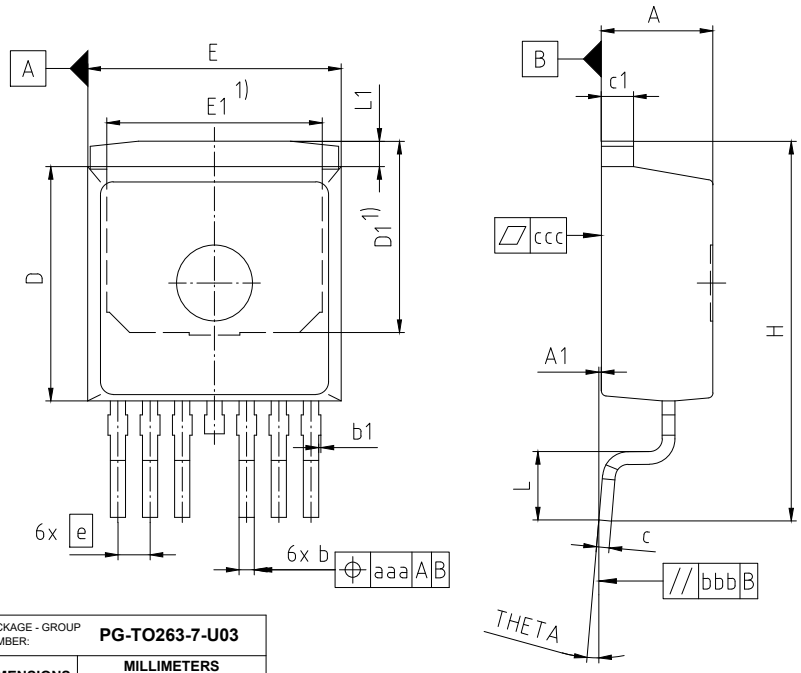
$V_{BR(DSS)}$=f(T_j); I_D=1 mA

Gate charge waveforms



-

5 Package outlines



PACKAGE - GROUP NUMBER:	PG-TO263-7-U03	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	4.30	4.50
A1	0.00	0.20
b	0.50	0.70
b1	0.00	0.15
c	0.40	0.60
c1	1.17	1.37
D	9.05	9.45
D1	7.45	7.65
E	9.80	10.20
E1	8.40	8.60
e	1.27	
N	7	
H	14.90	15.10
L	2.40	3.00
L1	0.70	1.30
THETA	---	8.00°
aaa	0.25	
bbb	0.10	
ccc	0.05	

NOTES:
1) TYPICAL METAL SURFACE. MIN. X=7.25 MM / Y= 6.9 MM
ALL METAL SURFACES: TIN PLATED, EXPECT AREA OF CUT

Figure 1 Outline PG-TO263-7, dimensions in mm

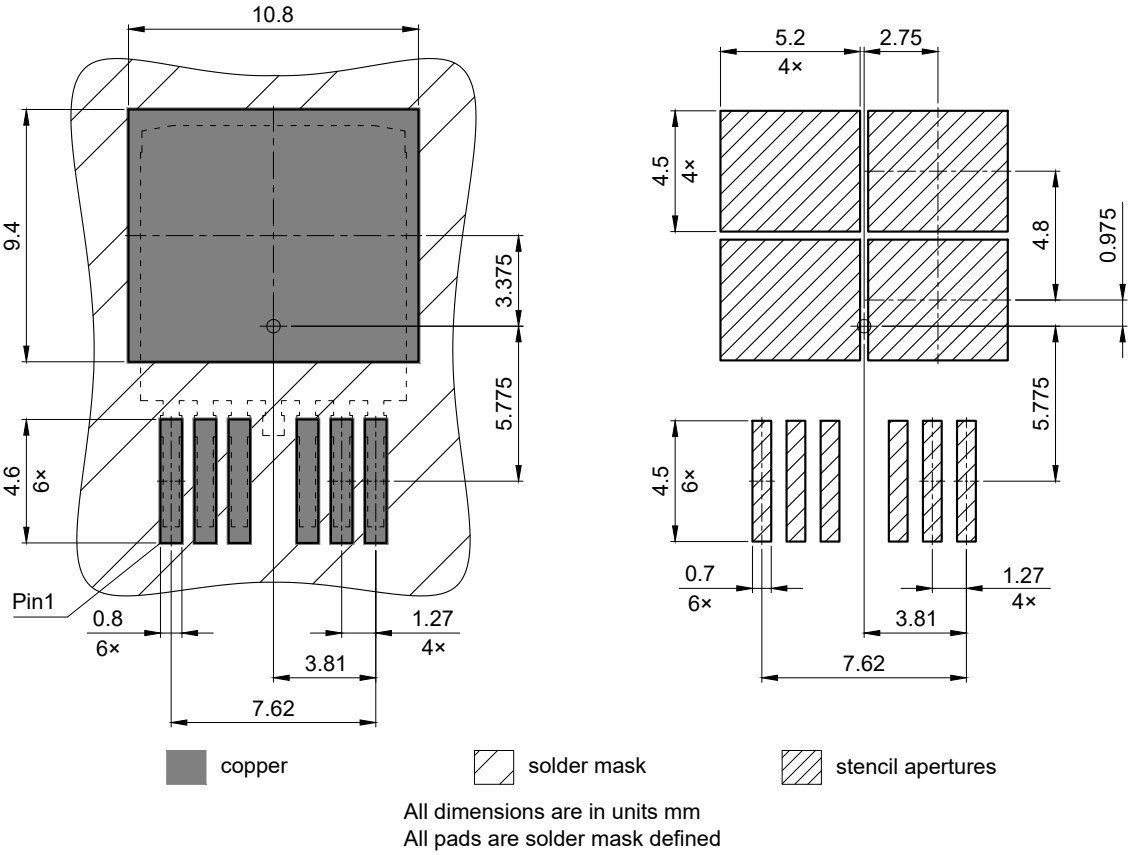


Figure 2 Footprint drawing PG-TO263-7, dimensions in mm

Revision history

IPF018N10NM5LF2

Revision 2025-01-24, Rev. 1.0

Previous revisions

Revision	Date	Subjects (major changes since last revision)
1.0	2025-01-24	Release of final datasheet

Published by
Infineon Technologies AG
81726 München, Germany